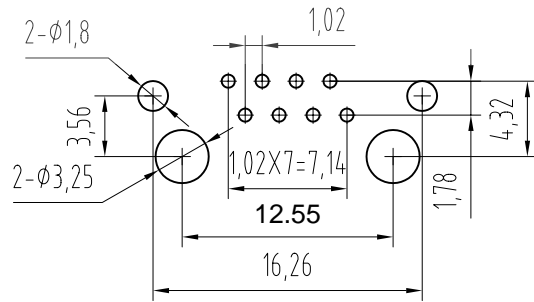
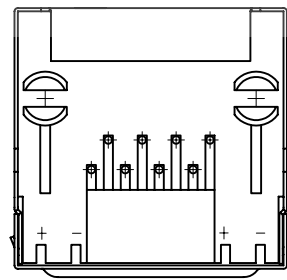
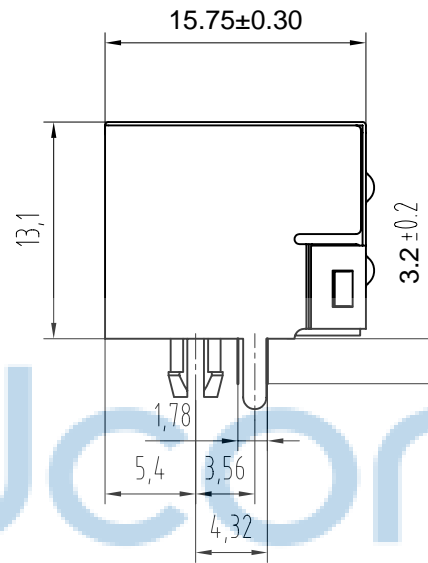
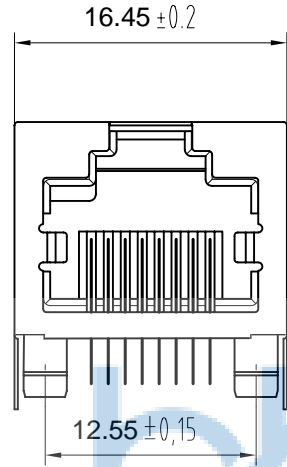


REV.	ECN NO	CONTENT	DATE	ENGINEER
A0		Initial release	/	SGF



PC Board Layout
Component Side Shown

NOTES:

MATERIAL :

- 1.HOUSING MATERIAL :GLASS FILLED POLYESTER UL94V-0.
- 2.CONTACT MATERIAL :PHOSPHOR BRONZE φ0.46mm.
- 3.PLATING :GOLD PLATING OVER NICKEL.
- 4.SHIELD :0.23mm THICKNESS COPPER ALLOY WITH NICKEL PLATED.

ELECTRICAL:

- 1.VOLTAGE RATING :125 VAC RMS.
- 2.CURRENT RATING :1.5 AMP.
- 3.CONTACT RESISTANCE :30 MILLIOHMS MAX.
- 4.INSULATION RESISTANCE :500 MEGOHMS MIN @ 500V DC .
- 5.DIELECTRIC WITHSTANDING RESISTANCE :1000V AC RMS 50Hz. 1MIN.

MECHANICAL:

- 1.DURRABILITY :750 CYCLES MIN.
- 2.PCB RETENTION PRE-SOLDER :1 LB MIN.

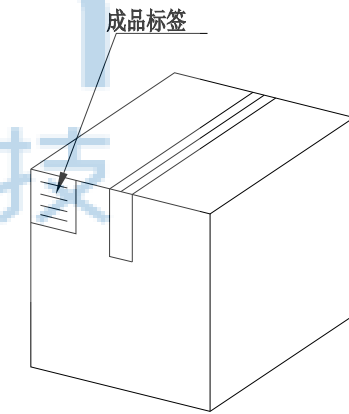
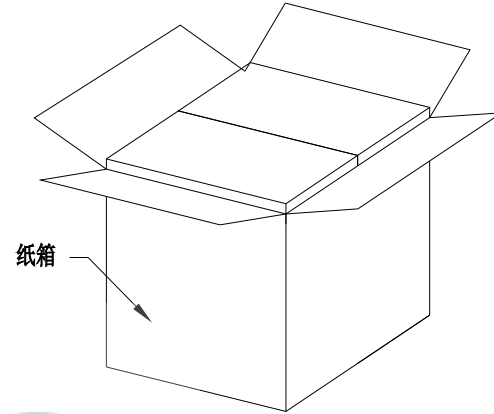
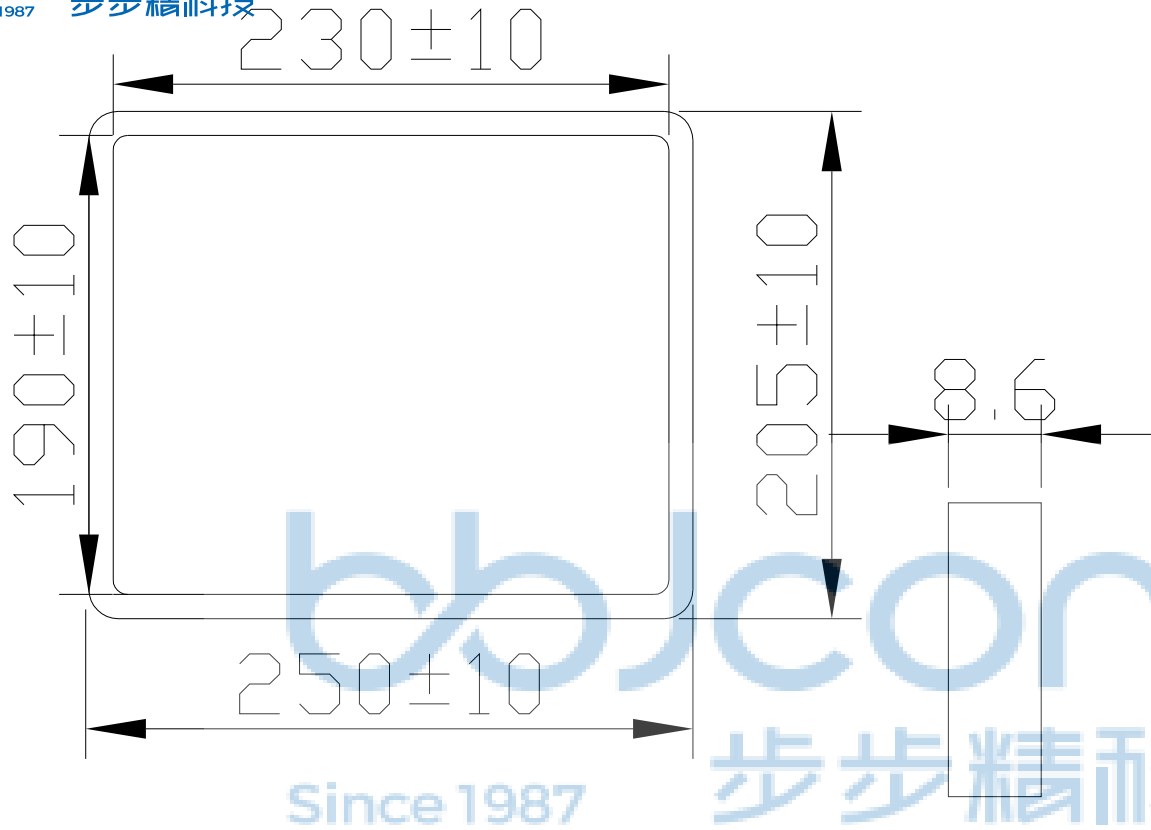
ENVIRONMENTAL:

- 1.STORAGE : -40℃~+85℃
- 2. OPERATION : 0℃ TO 70℃.



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.X: ±0.38 .XX: ±0.25 .XXX: ±0.13		X*: ±3* .X*: ±2* XX*: ±1*		APPD. JM_Zheng CHKD. LYX	
PDWG.NO: 0061-1		DR. SGF		PJ. NO.: RJ.01.22-11-2003 SIZE: A4 DRW NO.: FINISH: SEE NOTES MAT'L.: SEE NOTES SCALE: N/A REV.: A0 UNIT: mm PAGE: 1/2	

REV.	ECN NO	CONTENT	DATE	ENGINEER
A0		Initial release	/	SGF



纸箱规格: 350*210*290

1. 包装要求:
- 1.1 每盒吸塑盒包装100pcs;
 - 1.2 每20盘放一箱, 共计2000PCS;
 - 1.3 纸箱外贴上标签

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.X: ±0.38 .XX: ±0.25 .XXX: ±0.13		X*: ±3* .X*: ±2* .XX*: ±1*	
APPD.	JM_Zheng	NAME: RJ45 90度 L=15.75 无灯 无弹 带壳 不带滤波	
CHKD.	LYX	PJ. NO.: RJ.01.22-11-2003	
DR.	SGF	SIZE: A4 DRW NO.:	
PDWG.NO: 0061-1		FINISH: SEE NOTES MAT'L.: SEE NOTES	
		SCALE: N/A REV.: A0 UNIT: mm PAGE: 2/2	